AMENDMENTS TO THE CLAIMS

Please amend the claims as indicated below.

1-21 (canceled)

- 22 (currently amended) A plating apparatus for plating a workpiece having a surface to be plated using a plating solution, the plating apparatus comprising:
 - a plating tank for holding thea plating solution;
- a holder for holding thea workpiece and bringing thea surface to be plated of the workpiece into contact with the plating solution in the plating tank; and
- a ring-shaped nozzle pipe for immersing in the plating solution held in the plating tank, the nozzle pipe being disposed in the plating tank and having a plurality of plating solution injection nozzles for injecting the plating solution toward the surface to be plated of the workpiece held by the holder to supply the plating solution into the plating tank.
- 23 (currently amended) A plating apparatus according to claim 22,

 wherein the plating solution is injected in streams from the injection nozzles, and

 wherein the streams of the plating solution injected from the plating solution-injection
 nozzles intersectjoin each other on or in front of a substantially central area of the surface to be

 plated of the workpiece held by the holder.
- 24 (currently amended) A plating apparatus according to claim 22, wherein the plating apparatus comprises further comprising

an electroplating apparatus having an anode, and

wherein a plating voltage is applied between the anode and the workpiece to perform electroplating on the workpiece.

25 (previously presented) A plating apparatus according to claim 24, further comprising a plating solution injection nozzle for injecting the plating solution toward the anode to supply the plating solution into the plating tank.

- **26 (currently amended)** A plating apparatus according to claim 22, wherein the plating apparatus comprises further comprising an electroless plating apparatus for bringing an electroless plating solution into contact with the surface to be plated of the workpiece to perform electroless plating on the workpiece.
- **27 (currently amended)** A plating apparatus according to claim 22, wherein the workpiece is disposed horizontally <u>during plating</u>.
- **28 (currently amended)** A plating apparatus according to claim 22, wherein the workpiece is disposed vertically <u>during plating</u>.
- **29** (**previously presented**) A plating apparatus according to claim 22, wherein the nozzle pipe is shaped to extend along an outer profile of the workpiece.
- **30 (currently amended)** A plating apparatus according to claim 22, wherein the nozzle pipe is movable <u>relative</u>relatively to the workpiece held by the holder.
- **31 (previously presented)** A plating apparatus according to claim 22, wherein the nozzle pipe and/or the plating solution injection nozzles are made of an electrically insulating material.
- 32 (currently amended) A plating apparatus for plating a workpiece having a surface to be plated using a plating solution, the plating apparatus comprising:
 - a plating tank for holding a plating solution; and
- a stirring mechanism having a stirring vane <u>for immersingimmersed</u> in the plating solution in the plating tank and <u>disposingdisposed</u> in a position facing <u>thea</u> surface to <u>be plated</u> of <u>thea</u> workpiece, the stirring vane being reciprocally movable parallel to the surface to <u>be plated</u> of the workpiece to stir the plating solution <u>and having</u>; wherein the stirring vane has irregularities on at least one side thereof <u>for generating swirls in the plating solution when the stirring vane is reciprocally moved</u>, the irregularities <u>comprisingeomprise</u> a succession of triangular or rectangular saw-tooth irregularities, or a number of narrow grooves defined at

predetermined intervals.

- 33 (currently amended) A plating apparatus according to claim 32, wherein <u>athe</u> side of the <u>at least one side of the</u> stirring vane <u>having with</u> the irregularities provided thereon faces the surface to be plated of the workpiece.
- 34 (currently amended) A plating apparatus according to claim 32, wherein the stirring mechanism has a plurality of the stirring vanes.
- 35 (currently amended) A plating apparatus for plating a workpiece having a surface to be plated using a plating solution, the plating apparatus comprising:
 - a plating tank for holding a plating solution; and
- a stirring mechanism having a <u>plurality of stirring vanes having stirring surfaces for immersing stirring vane immersed</u> in the plating solution in the plating tank <u>and</u> for stirring the plating solution.;

wherein the stirring vane comprises a plurality of stirring vanes which are actuatable by respective independent drive mechanisms, the plurality of stirring vanes having respective edges which are aligned with each other to keep stirring surfaces of the plurality of stirring vanes in alignment with each other.

- 36 (currently amended) A plating apparatus according to claim 35, wherein the stirring vanes of the plurality of stirring vanes are different in shape from each other.
- 37 (currently amended) A plating apparatus according to claim 35, wherein the <u>plurality of</u> stirring vanes are reciprocally movable in directions parallel to <u>thea</u> surface to be plated of <u>thea</u> workpiece.
- 38 (currently amended) A plating apparatus for plating a workpiece having a surface to be plated using a plating solution, the plating apparatus comprising:
 - a plating tank for holding a plating solution; and
 - a stirring mechanism having a stirring vane for immersing immersed in the plating

solution in the plating tank and <u>disposingdisposed</u> in a position facing <u>thea</u> surface to be plated of <u>thea</u> workpiece, the stirring vane being <u>mounted on a rotational shaft and reciprocally movable</u> parallel to the surface to be plated of the workpiece to stir the plating solution;

wherein the stirring vane <u>is operable to formhas</u> an angle with respect to the surface to be plated of the workpiece which is, the angle being variable as the stirring vane reciprocally moves and the direction in which the stirring vane moves is changed by angular movement of the rotational shaft.

39 (currently amended) A plating apparatus according to claim 38, wherein the stirring mechanism has a plurality of the stirring vanes.